

SPECIFICATION

• Supplier : Samsung electro-mechanics • Samsung P/N : CL03C9R1BA3GNNC

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 9.1 pF, 25V, ±0.1 pF, C0G, 0201

A. Samsung Part Number

<u>CL</u> <u>03</u> <u>C</u> <u>9R1</u> <u>B</u> <u>A</u> <u>3</u> <u>G</u> <u>N</u> <u>N</u> <u>C</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

| 1 | Series | Samsung Multi-layer Ceramic Capacitor | | |
|-----|---------------|---------------------------------------|-------------------|-------------------------|
| 2 | Size | 0201 (inch code) | L: 0.6 ± 0.03 mm | W: 0.3 ± 0.03 mm |
| | | | _ | |
| 3 | Dielectric | C0G | 8 Inner electrode | Cu |
| 4 | Capacitance | 9.1 pF | Termination | Cu |
| (5) | Capacitance | ±0.1 _p F | Plating | Sn 100% (Pb Free) |
| | tolerance | | Product | Normal |
| 6 | Rated Voltage | 25 V | Special | Reserved for future use |
| 7 | Thickness | 0.3 ± 0.03 mm | ① Packaging | Cardboard Type, 7" reel |

B. Samsung Reliablility Test and Judgement condition

| | Performance | Test condition | |
|-------------------------------------|--|---------------------------------------|--|
| Capacitance | Within specified tolerance | 1Mb±10% 0.5~5Vrms | |
| Q | 582 min | | |
| Insulation 10,000Mohm or 500Mohm·μF | | Rated Voltage 60~120 sec. | |
| Resistance | Whichever is Smaller | | |
| Appearance | No abnormal exterior appearance | Microscope (×10) | |
| Withstanding | No dielectric breakdown or | 300% of the rated voltage | |
| Voltage | mechanical breakdown | | |
| Temperature | COG | | |
| Characterisitcs | (From -55 ℃ to 125 ℃, Capacitance change shoud be within ±30PPM/℃) | | |
| Adhesive Strength | No peeling shall be occur on the | 200g·F, for 10±1 sec. | |
| of Termination | terminal electrode | | |
| Bending Strength | Capacitance change : | Bending to the limit (1mm) | |
| | within ±5% or ±0.5pF whichever is larger | with 1.0mm/sec. | |
| Solderability | More than 75% of terminal surface | 1) Sn63Pb37 solder | |
| | is to be soldered newly | 235±5℃, 5±0.5sec. | |
| | | 2) SnAg3.0Cu0.5 solder | |
| | | 245±5℃, 3±0.3sec. | |
| | | (preheating : 80~120 ℃ for 10~30sec.) | |
| Resistance to Capacitance change : | | Solder pot : 270±5℃, 10±1sec. | |
| Soldering heat | within ±2.5% or ±0.25pF whichever is larger | | |
| | Tan δ, IR : initial spec. | | |

| | Performance | Test condition |
|------------------|---|-------------------------------------|
| Vibration Test | Capacitance change : | Amplitude : 1.5mm |
| | within ±2.5% or ±0.25pF whichever is larger | From 10Hz to 55Hz (return : 1min.) |
| | Tan δ, IR : initial spec. | 2hours × 3 direction (x, y, z) |
| Humidity | Capacitance change : | 40±2℃, 90~95%RH, 500+12/-0hrs |
| | within ±5% or ±0.5pF whichever is larger | |
| Q: 291 min | | |
| | IR: 1000Mohm or 50Mohm · μF | |
| | Whichever is Smaller | |
| Moisture | Capacitance change : | With rated voltage |
| Resistance | within ±7.5% or ±0.75pF whichever is larger | 40±2℃, 90~95%RH, 500+12/-0hrs |
| | Q: 130.33 min | |
| | IR: 500Mohm or 25Mohm · μF | |
| | Whichever is Smaller | |
| High Temperature | Capacitance change : | With 200% of the rated voltage |
| Resistance | within ±3% or ±0.3pF whichever is larger | Max. operating temperature |
| | Q: 291 min | 1000+48/-0hrs |
| | IR : 1000Mohm or 50Mohm · μF | |
| | Whichever is Smaller | |
| Temperature | Capacitance change : | 1 cycle condition |
| Cycling | within ±2.5% or ±0.25pF whichever is larger | Min. operating temperatur → 25 °C |
| | Tan δ, IR : initial spec. | → Max. operating temperature → 25°C |
| | | |
| | | |
| | | 5 cycle test |

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5 $^{\circ}\!\!\mathrm{C}$, 10sec. Max)

^{*} For the more detail Specification, Please refer to the Samsung MLCC catalogue.